



Material Content Data Sheet



Sales Product Name				BGSX 22G2A10 E6327		Issued		1. August 2018	
MA#				MA001728396					
Package				PG-ATSLP-10-2		Weight*		2.48 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.543	21.87	21.87	218719	218719	
bumps	non noble metal	copper	7440-50-8	0.014	0.55	0.55	5486	5486	
encapsulation	organic material	carbon black	1333-86-4	0.007	0.26		2643		
	plastics	epoxy resin	-	0.190	7.66		76633		
leadfinish	inorganic material	silicondioxide	60676-86-0	1.115	44.93	52.85	449228	528504	
	noble metal	gold	7440-57-5	0.028	1.11		11094		
substrate	non noble metal	nickel	7440-02-0	0.031	1.27	2.38	12653	23747	
	organic material	carbon black	1333-86-4	0.001	0.03		308		
	plastics	epoxy resin	-	0.030	1.20		12006		
	inorganic material	silicondioxide	60676-86-0	0.224	9.03		90306		
ubm	non noble metal	copper	7440-50-8	0.229	9.23	19.49	92301	194921	
	non noble metal	tungsten	7440-33-7	0.000	0.00		15		
solder	non noble metal	titanium	7440-32-6	0.000	0.00		29		
	non noble metal	copper	7440-50-8	0.000	0.01	0.01	83	127	
solder resists	noble metal	silver	7440-22-4	0.000	0.00		46		
	non noble metal	tin	7440-31-5	0.005	0.20	0.20	1966	2012	
	inorganic material	silicondioxide	60676-86-0	0.014	0.56		5628		
	inorganic material	bariumsulfate	7727-43-7	0.014	0.57		5694		
*deviation	plastics	acrylic resin	-	0.038	1.52	2.65	15162	26484	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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